

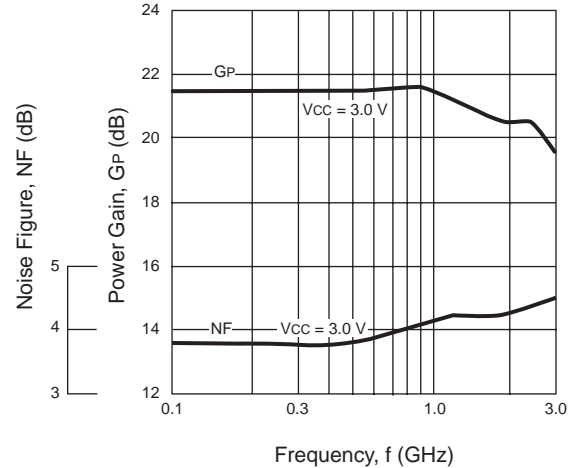
## 3 V, 2.9 GHz SILICON MMIC MEDIUM OUTPUT POWER AMPLIFIER FOR MOBILE COMMUNICATIONS

### UPC8182TB

### FEATURES

- **SUPPLY VOLTAGE:**  
V<sub>CC</sub> = 2.7 to 3.3 V
- **CIRCUIT CURRENT:**  
I<sub>CC</sub> = 30 mA TYP at V<sub>CC</sub> = 3.0 V
- **MEDIUM OUTPUT POWER:**  
P<sub>O(1dB)</sub> = +9.5 dBm TYP at f = 0.9 GHz  
P<sub>O(1dB)</sub> = +9.0 dBm TYP at f = 1.9 GHz  
P<sub>O(1dB)</sub> = +8.0 dBm TYP at f = 2.4 GHz
- **POWER GAIN:**  
G<sub>P</sub> = 21.5 dB TYP at f = 0.9 GHz  
G<sub>P</sub> = 20.5 dB TYP at f = 1.9 GHz  
G<sub>P</sub> = 20.5 dB TYP at f = 2.4 GHz
- **UPPER LIMIT OPERATING FREQUENCY:**  
f<sub>U</sub> = 2.9 GHz TYP at 3 dB bandwidth
- **HIGH-DENSITY SURFACE MOUNTING:**  
6-pin super minimold package (2.0 x 1.25 x 0.9 mm)

NOISE FIGURE, POWER GAIN vs. FREQUENCY



### DESCRIPTION

The UPC8182TB is a silicon monolithic integrated circuit designed as amplifier for mobile communications. This IC has low current consumption and wider band than UPC2771TB.

This IC is manufactured using NEC's 25 GHz ft UHSO silicon bipolar process. This process uses direct silicon nitride passivation film and gold electrodes. These materials can protect the chip surface from pollution and prevent corrosion/migration. This IC has excellent performance, uniformity, and reliability.

### APPLICATIONS

- Buffer amplifiers for 1.9 GHz to 2.4 GHz mobile communication system.

### ELECTRICAL CHARACTERISTICS

(T<sub>A</sub> = 25°C, V<sub>CC</sub> = V<sub>OUT</sub> = 3.0 V, Z<sub>S</sub> = Z<sub>L</sub> = 50Ω)

PART NUMBER PACKAGE OUTLINE			UPC8182TB S06		
SYMBOLS	PARAMETERS AND CONDITIONS	UNITS	MIN	TYP	MAX
I <sub>CC</sub>	Circuit Current (no signal)	mA	22.0	30.0	38.0
G <sub>P</sub>	Power Gain, f = 0.9 GHz f = 1.9 GHz f = 2.4 GHz	dB	19.0 17.5 18.0	21.5 20.5 20.5	25.0 23.5 24.0
N <sub>F</sub>	Noise Figure, f = 0.9 GHz f = 1.9 GHz f = 2.4 GHz	dB	— — —	4.5 4.5 5.0	6.0 6.0 6.5
f <sub>U</sub>	Upper Limit Operating Frequency, 3 dB down below from gain at f = 1.0 GHz	GHz	2.8	2.9	
ISL	Isolation, f = 0.9 GHz f = 1.9 GHz f = 2.4 GHz	dB	30 27 28	33 32 31	— — —

**ELECTRICAL CHARACTERISTICS, cont.**

( $T_A = 25^\circ\text{C}$ ,  $V_{CC} = V_{OUT} = 3.0\text{ V}$ ,  $Z_S = Z_L = 50\Omega$ )

PART NUMBER PACKAGE OUTLINE			UPC8182TB S06		
SYMBOLS	PARAMETERS AND CONDITIONS	UNITS	MIN	TYP	MAX
RLin	Input Return Loss, f = 0.9 GHz f = 1.9 GHz f = 2.4 GHz	dB	6	8	–
			8	10	–
			9	12	–
RLout	Output Return Loss, f = 0.9 GHz f = 1.9 GHz f = 2.4 GHz	dB	8	10	–
			9	11	–
			11	14	–
PO(1dB)	1 dB Gain Compression Output Level, f = 0.9 GHz f = 1.9 GHz f = 2.4 GHz	dBm	+7.5	+9.5	–
			+7.0	+9.0	–
			+5.5	+8.0	–
PO(SAT)	Saturated Output Power Level, f = 0.9 GHz, PIN = -5 dBm f = 1.9 GHz, PIN = -5 dBm f = 2.4 GHz, PIN = -5 dBm	dBm	–	+10.5	–
			–	+10.0	–
			–	+9.5	–

**ABSOLUTE MAXIMUM RATINGS<sup>1</sup>** ( $T_A = +25^\circ\text{C}$ )

SYMBOLS	PARAMETERS	UNITS	RATINGS
VCC	Supply Voltage <sup>2</sup>	V	3.6
ICC	Total Circuit Current	mA	60
PD	Power Dissipation <sup>3</sup>	mW	200
TA	Operating Ambient Temperature	°C	-40 to +85
TSTG	Storage Temperature	°C	-55 to +150
PIN	Input Power	dBm	+10

Notes:

1. Operation in excess of any one of these conditions may result in permanent damage.
2.  $T_A = 25^\circ\text{C}$ , pins 4 and 6.
3. Mounted on a double-sided copper clad 50x50x1.6 mm epoxy glass PWB,  $T_A = +85^\circ\text{C}$ .

**RECOMMENDED OPERATING CONDITIONS**

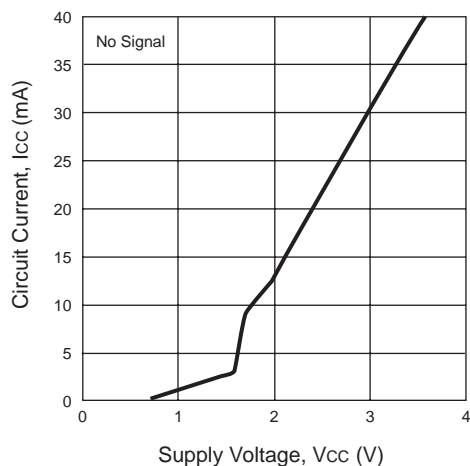
SYMBOLS	PARAMETERS	UNITS	MIN	TYP	MAX
VCC	Supply Voltage <sup>1</sup>	V	2.7	3.0	3.3
TA	Ambient Temperature	°C	-40	+25	+85

Note:

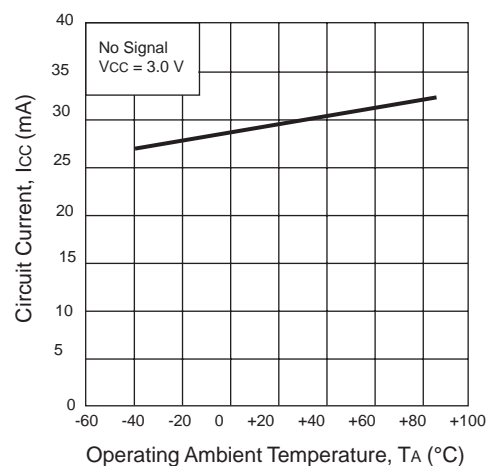
1. Same voltage applied to pins 4 and 6

**TYPICAL PERFORMANCE CURVES** (Unless otherwise specified,  $T_A = 25^\circ\text{C}$ )

**CIRCUIT CURRENT vs. SUPPLY VOLTAGE**

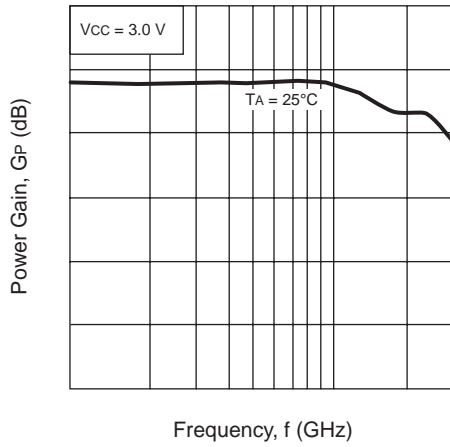


**CIRCUIT CURRENT vs. OPERATING AMBIENT TEMPERATURE**

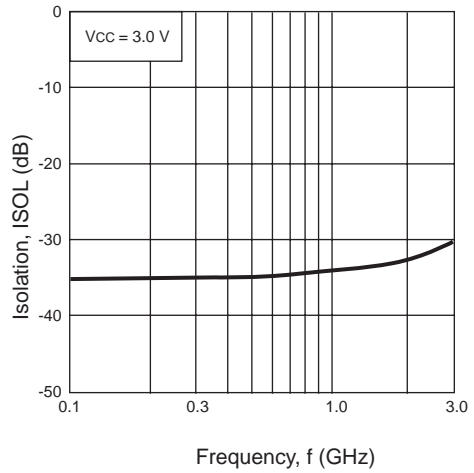


**TYPICAL PERFORMANCE CURVES, cont.** (Unless otherwise specified,  $T_A = 25^\circ\text{C}$ )

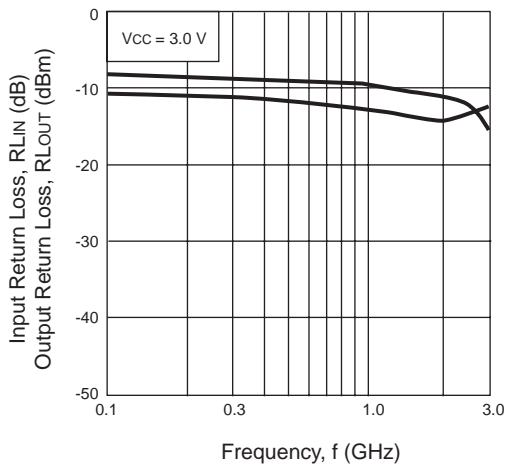
**POWER GAIN vs. FREQUENCY**



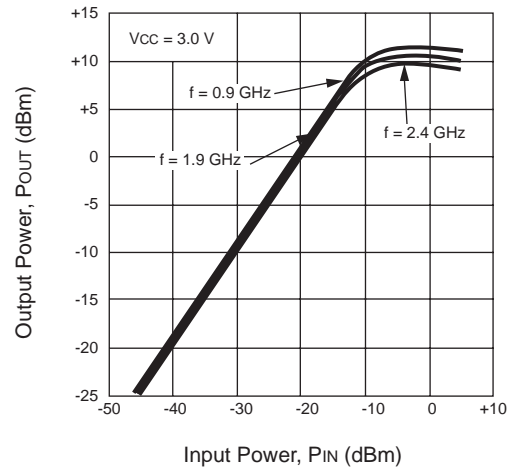
**ISOLATION vs. FREQUENCY**



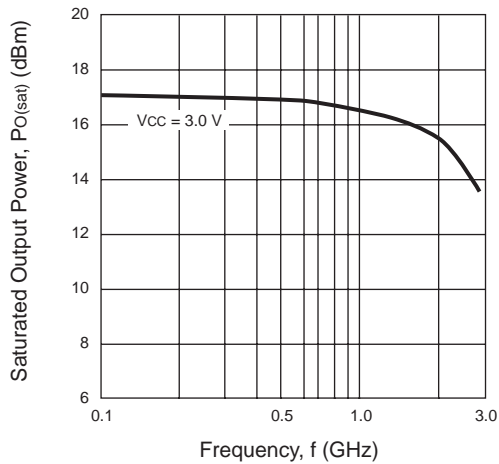
**INPUT RETURN LOSS, OUTPUT RETURN LOSS vs. FREQUENCY**



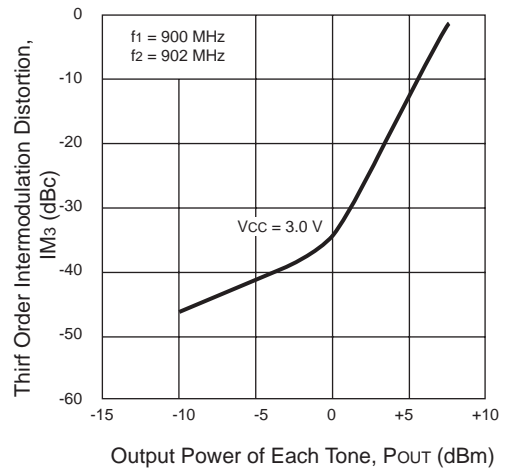
**OUTPUT POWER vs. INPUT POWER**



**SATURATED OUTPUT POWER vs. FREQUENCY**

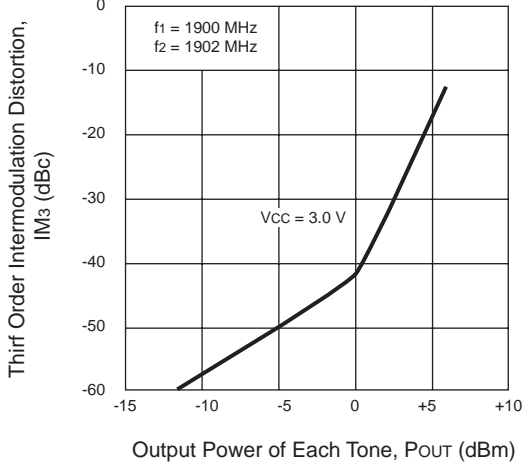


**THIRD ORDER INTERMODULATION DISTORTION vs. OUTPUT POWER OF EACH TONE**

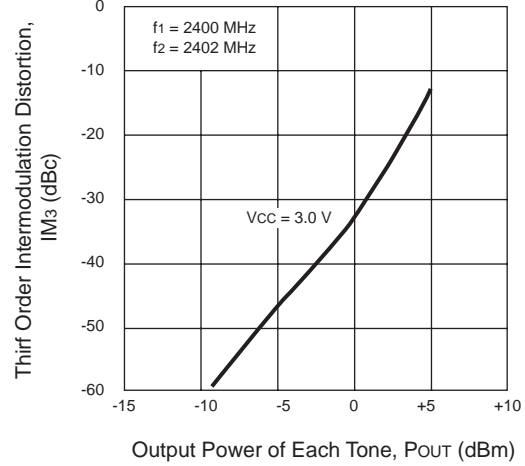


**TYPICAL PERFORMANCE CURVES** (Unless otherwise specified,  $T_A = 25^\circ\text{C}$ )

**THIRD ORDER INTERMODULATION DISTORTION vs. OUTPUT POWER OF EACH TONE**



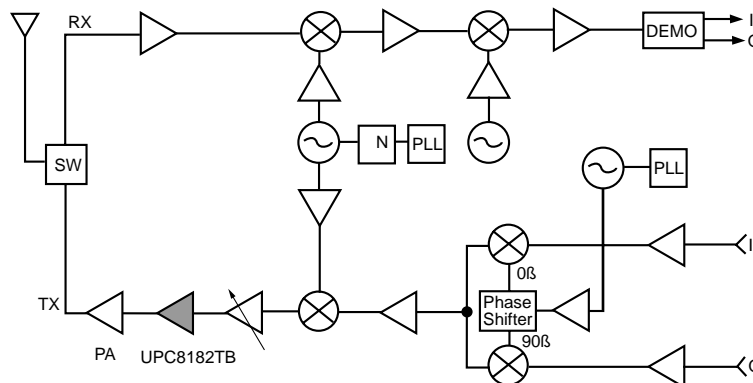
**THIRD ORDER INTERMODULATION DISTORTION vs. OUTPUT POWER OF EACH TONE**



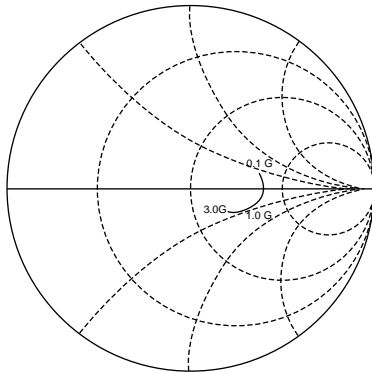
**PIN FUNCTIONS** (Pin Voltage is measured at  $V_{CC} = 3.0\text{ V}$ )

Pin No.	Pin Name	Applied Voltage	Pin Voltage	Description	Equivalent Circuit
1	INPUT	—	—	Signal input pin. A internal matching circuit, configured with resistors, enables $50\ \Omega$ connection over a wide band. A multi-feedback circuit is designed to cancel the deviations of $h_{FE}$ and resistance. This pin must be coupled to signal source with capacitor for DC cut.	
4	OUTPUT	Voltage same as $V_{CC}$ through external inductor	—	Signal output pin. The inductor must be attached between $V_{CC}$ and output pins to supply current to the internal output transistors.	
6	$V_{CC}$	2.7 to 3.3	—	Power supply pin, which biases the internal input transistor. This pin should be externally equipped with bypass capacitor to minimize its impedance.	
2 3 5	GND	0	—	GND pin. This pin should be connected to the system ground with minimum inductance. Ground pattern on the board should be formed as wide as possible. All the ground pins must be connected together with wide ground pattern to decrease impedance difference.	

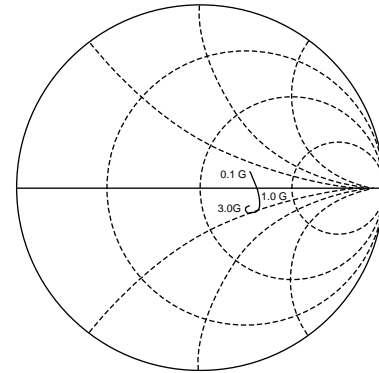
**APPLICATION EXAMPLE** (Digital Cellular Telephone)



**TYPICAL SCATTERING PARAMETERS** (TA = 25°C)



S11



S22

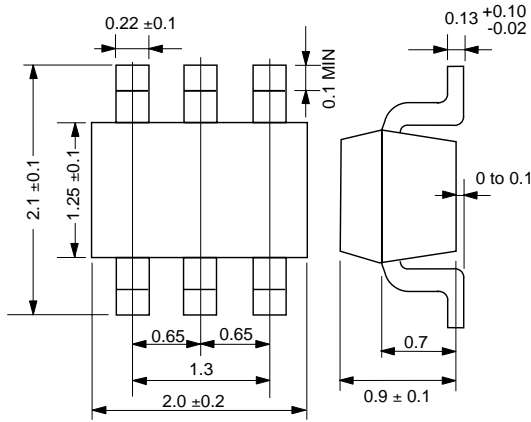
Frequency in GHz  
Vcc = Vout = 3.0 V, Icc = 30.0 mA

Vcc = Vout = 3.0 V, Icc = 30.0 mA

FREQUENCY GHz	S11		S21		S12		S22		K
	MAG	ANG	MAG	ANG	MAG	ANG	MAG	ANG	
0.1	0.452	-2.7	9.078	-2.0	0.020	4.3	0.338	-1.6	1.89
0.1	0.391	-2.6	12.933	-4.4	0.016	1.8	0.293	-2.7	1.84
0.2	0.391	-6.2	12.999	-8.0	0.017	3.5	0.287	-5.1	1.80
0.3	0.387	-10.2	13.174	-11.8	0.016	7.6	0.282	-6.8	1.86
0.4	0.382	-13.8	13.322	-16.4	0.016	9.2	0.279	-8.4	1.82
0.5	0.371	-16.7	13.391	-20.7	0.017	13.2	0.276	-9.1	1.79
0.6	0.365	-19.5	13.407	-25.7	0.017	15.9	0.279	-10.0	1.78
0.7	0.354	-21.6	13.549	-30.4	0.018	21.0	0.278	-11.0	1.73
0.8	0.347	-23.7	13.475	-35.3	0.020	22.3	0.285	-11.7	1.57
0.9	0.343	-25.8	13.426	-40.1	0.020	21.2	0.290	-13.5	1.52
1.0	0.334	-28.1	13.474	-44.9	0.019	27.0	0.293	-15.1	1.62
1.1	0.330	-30.8	13.386	-50.0	0.018	28.1	0.296	-17.6	1.69
1.2	0.324	-32.1	13.185	-54.6	0.020	27.6	0.302	-20.3	1.61
1.3	0.317	-34.2	13.121	-59.4	0.020	31.7	0.303	-21.9	1.62
1.4	0.318	-35.7	13.151	-64.2	0.021	32.1	0.309	-24.6	1.51
1.5	0.313	-38.0	12.866	-69.4	0.022	34.0	0.315	-27.1	1.47
1.6	0.309	-39.8	12.814	-73.9	0.023	34.6	0.318	-29.5	1.43
1.7	0.303	-42.5	12.508	-78.2	0.022	34.3	0.314	-33.1	1.52
1.8	0.302	-44.3	12.357	-83.2	0.024	35.9	0.319	-35.6	1.44
1.9	0.298	-45.5	12.090	-86.7	0.026	36.9	0.322	-37.6	1.39
2.0	0.290	-47.5	12.035	-90.9	0.025	40.0	0.313	-40.5	1.43
2.1	0.291	-50.1	11.984	-95.4	0.027	36.5	0.321	-43.5	1.36
2.2	0.283	-52.6	11.662	-99.9	0.026	38.2	0.314	-46.0	1.43
2.3	0.277	-54.1	11.711	-104.0	0.027	40.0	0.310	-48.6	1.41
2.4	0.274	-56.7	11.629	-108.6	0.028	38.4	0.309	-51.6	1.37
2.5	0.270	-58.0	11.475	-113.7	0.029	39.1	0.304	-54.1	1.35
2.6	0.261	-59.8	11.308	-118.5	0.029	39.9	0.297	-55.3	1.39
2.7	0.264	-61.4	11.198	-123.5	0.032	38.6	0.303	-56.5	1.29
2.8	0.253	-62.0	10.803	-129.4	0.031	42.8	0.295	-57.3	1.39
2.9	0.258	-63.9	10.670	-134.8	0.032	41.3	0.307	-57.9	1.33
3.0	0.255	-65.7	10.086	-139.5	0.033	40.9	0.316	-60.0	1.35
3.1	0.250	-67.9	9.683	-145.4	0.032	39.8	0.321	-63.1	1.44

**OUTLINE DIMENSIONS** (Units in mm)

**PACKAGE OUTLINE S06**

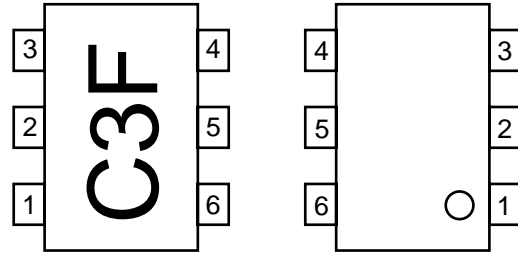


Note:  
All dimensions are typical unless otherwise specified.

**LEAD CONNECTIONS**

(Top View)

(Bottom View)



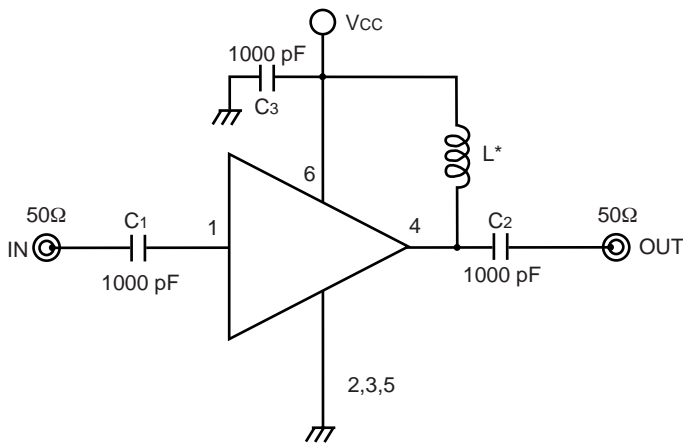
- 1. INPUT
- 2. GND
- 3. GND
- 4. OUTPUT
- 5. GND
- 6. Vcc

**ORDERING INFORMATION**

PART NUMBER	QUANTITY
UPC8182TB-E3	3K/Reel

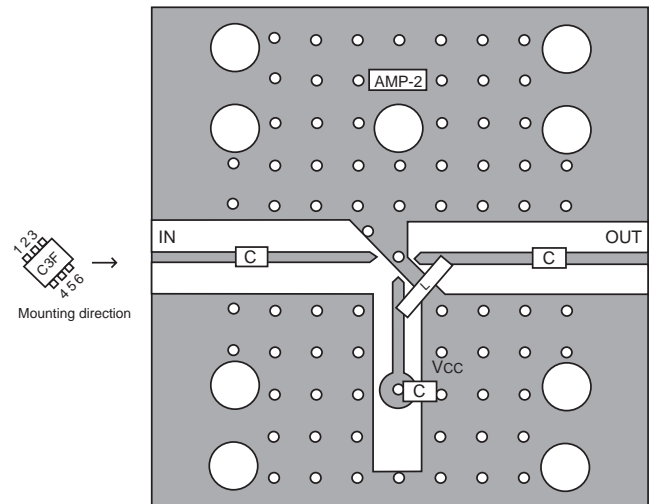
Note: Embossed tape 8 mm wide. Pins 1,2,3 face tape perforation side.

**TEST CIRCUIT**



\*L: 100 nH for f = 100 MHz and higher  
10 nH for f = 2.0 GHz and higher

**APPLICATION BOARD**



**Life Support Applications**

These NEC products are not intended for use in life support devices, appliances, or systems where the malfunction of these products can reasonably be expected to result in personal injury. The customers of CEL using or selling these products for use in such applications do so at their own risk and agree to fully indemnify CEL for all damages resulting from such improper use or sale.